National Semiconductor

March 1998

LPC660
Low Power CMOS Quad Operational Amplifier

General Description

The LPC660 CMOS Quad operational amplifier is ideal for operation from a single supply. It features a wide range of operating voltages from +5V to +15V and features rail-to-rail output swing in addition to an input common-mode range that includes ground. Performance limitations that have plagued CMOS amplifiers in the past are not a problem with this design. Input V_{OS}, drift, and broadband noise as well as voltage gain (into 100 kΩ and 5 kΩ) are all equal to or better than widely accepted bipolar equivalents, while the power supply requirement is typically less than 1 mW.

This chip is built with National's advanced Double-Poly Silicon-Gate CMOS process.

See the LPC662 datasheet for a Dual CMOS operational amplifier and LPC661 datasheet for a single CMOS operational amplifier with these same features.

Applications

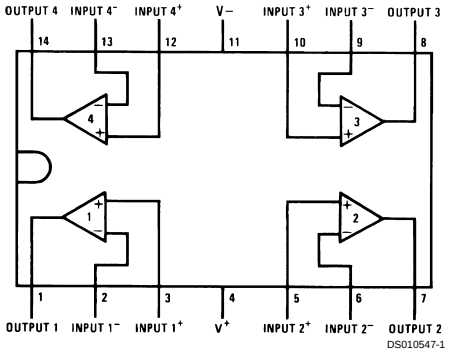
- High-impedance buffer
- Precision current-to-voltage converter
- Long-term integrator
- High-impedance preamplifier
- Active filter
- Sample-and-Hold circuit
- Peak detector

Features

- Rail-to-rail output swing
- Micropower operation: (1 mW)
- Specified for 100 kΩ and 5 kΩ loads
- High voltage gain: 120 dB
- Low input offset voltage: 3 mV
- Low offset voltage drift: 1.3 µV/°C
- Ultra low input bias current: 2 fA
- Input common-mode includes V^-
- Operation range from +5V to +15V
- Low distortion: 0.01% at 1 kHz
- Slew rate: 0.11 V/µs
- Full military temp. range available

Connection Diagram

14-Pin DIP/SO



Top View

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Ordering Information

Package	Temperature Range		NSC Drawing	Transport Media
	Military	Industrial		
14-Pin Side Brazed Ceramic DIP	LPC660AMD		D14E	Rail
14-Pin Small Outline		LPC660AIM or LPC660IM	M14A	Rail Tape and Reel
14-Pin Molded DIP		LPC660AIN or LPC660IN	N14A	Rail
14-Pin Ceramic DIP	LPC660AMJ/883		J14A	Rail

Absolute Maximum Ratings (Note 3)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Differential Input Voltage	±Supply Voltage
Supply Voltage ($V^+ - V^-$)	16V
Output Short Circuit to V^+	(Note 11)
Output Short Circuit to V^-	(Note 1)
Lead Temperature	
(Soldering, 10 sec.)	260˚C
Storage Temp. Range	−65˚C to +150˚C
Junction Temperature (Note 2)	150˚C
ESD Rating	
(C = 100 pF, R = 1.5 kΩ)	1000V
Power Dissipation	(Note 2)
Current at Input Pin	±5 mA
Current at Output Pin	±18 mA
Voltage at Input/Output Pin	(V^+) + 0.3V, (V^-) − 0.3V
Current at Power Supply Pin	35 mA

Operating Ratings (Note 3)

Temperature Range	
LPC660AM	$-55˚C \le T_J \le +125˚C$
LPC660AI	$-40˚C \le T_J \le +85˚C$
LPC660I	$-40˚C \le T_J \le +85˚C$
Supply Range	4.75V to 15.5V
Power Dissipation	(Note 9)
Thermal Resistance (θ_{JA}), (Note 10)	
14-Pin Ceramic DIP	90˚C/W
14-Pin Molded DIP	85˚C/W
14-Pin SO	115˚C/W
14-Pin Side Brazed Ceramic DIP	90˚C/W

DC Electrical Characteristics

Unless otherwise specified, all limits guaranteed for T_J = 25˚C. **Boldface** limits apply at the temperature extremes. V^+ = 5V, V^- = 0V, V_{CM} = 1.5V, V_O = 2.5V, and R_L > 1M unless otherwise specified.

Parameter	Conditions	Typ	LPC660AM LPC660AMJ/883	LPC660AI	LPC660I	Units
			Limit (Notes 4, 8)	Limit (Note 4)	Limit (Note 4)	
Input Offset Voltage		1	3	3	6	mV
			3.5	**3.3**	**6.3**	max
Input Offset Voltage Average Drift		1.3				µV/˚C
Input Bias Current		0.002	20			pA
			100	**4**	**4**	max
Input Offset Current		0.001	20			pA
			100	**2**	**2**	max
Input Resistance		>1				Tera Ω
Common Mode Rejection Ratio	0V ≤ V_{CM} ≤ 12.0V V^+ = 15V	83	70	70	63	dB
			68	**68**	**61**	min
Positive Power Supply Rejection Ratio	5V ≤ V^+ ≤ 15V	83	70	70	63	dB
			68	**68**	**61**	min
Negative Power Supply Rejection Ratio	0V ≤ V^- ≤ −10V	94	84	84	74	dB
			82	**83**	**73**	min
Input Common Mode Voltage Range	V^+ = 5V & 15V For CMRR > 50 dB	−0.4	−0.1	−0.1	−0.1	V
			0	**0**	**0**	max
		V^+ − 1.9	V^+ − 2.3	V^+ − 2.3	V^+ − 2.3	V
			V^+ − 2.6	**V^+ − 2.5**	**V^+ − 2.5**	min
Large Signal Voltage Gain	R_L = 100 kΩ (Note 5) Sourcing	1000	400	400	300	V/mV
			250	**300**	**200**	min
	Sinking	500	180	180	90	V/mV
			70	**120**	**70**	min
	R_L = 5 kΩ (Note 5) Sourcing	1000	200	200	100	V/mV
			150	**160**	**80**	min
	Sinking	250	100	100	50	V/mV
			35	**60**	**40**	min

DC Electrical Characteristics (Continued)

Unless otherwise specified, all limits guaranteed for T_J = 25˚C. **Boldface** limits apply at the temperature extremes. V^+ = 5V, V^- = 0V, V_{CM} = 1.5V, V_O = 2.5V, and R_L > 1M unless otherwise specified.

Parameter	Conditions	Typ	LPC660AM LPC660AMJ/883	LPC660AI	LPC660I	Units
			Limit (Notes 4, 8)	**Limit** (Note 4)	**Limit** (Note 4)	
Output Swing	V^+ = 5V	4.987	4.970	4.970	4.940	V
	R_L = 100 kΩ to $V^+/2$		**4.950**	**4.950**	**4.910**	min
		0.004	0.030	0.030	0.060	V
			0.050	**0.050**	**0.090**	max
	V^+ = 5V	4.940	4.850	4.850	4.750	V
	R_L = 5 kΩ to $V^+/2$		**4.750**	**4.750**	**4.650**	min
		0.040	0.150	0.150	0.250	V
			0.250	**0.250**	**0.350**	max
	V^+ = 15V	14.970	14.920	14.920	14.880	V
	R_L = 100 kΩ to $V^+/2$		**14.880**	**14.880**	**14.820**	min
		0.007	0.030	0.030	0.060	V
			0.050	**0.050**	**0.090**	max
	V^+ = 15V	14.840	14.680	14.680	14.580	V
	R_L = 5 kΩ to $V^+/2$		**14.600**	**14.600**	**14.480**	min
		0.110	0.220	0.220	0.320	V
			0.300	**0.300**	**0.400**	max
Output Current V^+ = 5V	Sourcing, V_O = 0V	22	16	16	13	mA
			12	**14**	**11**	min
	Sinking, V_O = 5V	21	16	16	13	mA
			12	**14**	**11**	min
Output Current V^+ = 15V	Sourcing, V_O = 0V	40	19	28	23	mA
			19	**25**	**20**	min
	Sinking, V_O = 13V (Note 11)	39	19	28	23	mA
			19	**24**	**19**	min
Supply Current	All Four Amplifiers V_O = 1.5V	160	200	200	240	µA
			250	**230**	**270**	max

AC Electrical Characteristics

Unless otherwise specified, all limits guaranteed for T_J = 25˚C. **Boldface** limits apply at the temperature extremes. V^+ = 5V, V^- = 0V, V_{CM} = 1.5V, V_O = 2.5, and R_L > 1M unless otherwise specified.

Parameter	Conditions	Typ	LPC660AM LPC660AMJ/883	LPC660AI	LPC660I	Units
			Limit (Notes 4, 8)	Limit (Note 4)	Limit (Note 4)	
Slew Rate	(Note 6)	0.11	0.07	0.07	0.05	V/µs
			0.04	**0.05**	**0.03**	min
Gain-Bandwidth Product		0.35				MHz
Phase Margin		50				Deg
Gain Margin		17				dB
Amp-to-Amp Isolation	(Note 7)	130				dB
Input Referred Voltage Noise	F = 1 kHz	42				$nV/\sqrt{Hz}$
Input Referred Current Noise	F = 1 kHz	0.0002				$pA/\sqrt{Hz}$
Total Harmonic Distortion	F = 1 kHz, A_V = −10 R_L = 100 kΩ, V_O = 8 V_{PP}	0.01				%

Note 1: Applies to both single supply and split supply operation. Continuous short circuit operation at elevated ambient temperature and/or multiple Op Amp shorts can result in exceeding the maximum allowed junction temperature of 150˚C. Output currents in excess of ±30 mA over long term may adversely affect reliability.

Note 2: The maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} and T_A. The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(max)}-T_A)\theta_{JA}$.

Note 3: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed.

Note 4: Limits are guaranteed by testing or correlation.

Note 5: V^+ = 15V, V_{CM} = 7.5V and R_L connected to 7.5V. For Sourcing tests, 7.5V ≤ V_O ≤ 11.5V. For Sinking tests, 2.5V ≤ V_O ≤ 7.5V.

Note 6: V^+ = 15V. Connected as Voltage Follower with 10V step input. Number specified is the slower of the positive and negative slew rates.

Note 7: Input referred. V^+ = 15V and R_L = 100 kΩ connected to $V^+/2$. Each amp excited in turn with 1 kHz to produce V_O = 13 V_{PP}.

Note 8: A military RETS electrical test specification is available on request. At the time of printing, the LPC660AMJ/883 RETS specification complied fully with the **boldface** limits in this column. The LPC660AMJ/883 may also be procured to a Standard Military Drawing specification.

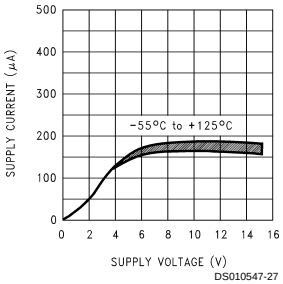
Note 9: For operating at elevated temperatures, the device must be derated based on the thermal resistance θ_{JA} with $P_D = (T_J-T_A)/\theta_{JA}$.

Note 10: All numbers apply for packages soldered directly into a PC board.

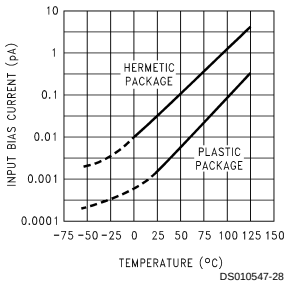
Note 11: Do not connect output to $V^+$when V^+ is greater than 13V or reliability may be adversely affected.

Typical Performance Characteristics V_S = ± 7.5V, T_A = 25˚C unless otherwise specified

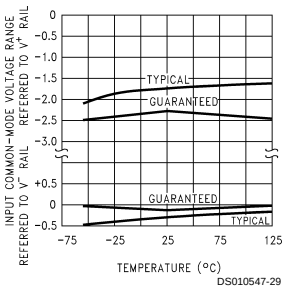
Supply Current vs Supply Voltage



Input Bias Current vs Temperature

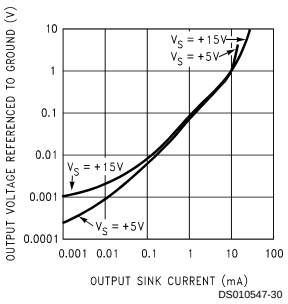


Common-Mode Voltage Range vs Temperature



Typical Performance Characteristics V_S = ± 7.5V, T_A = 25˚C unless otherwise specified (Continued)

Output Characteristics Current Sinking



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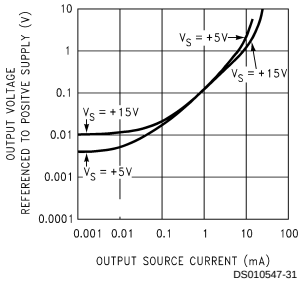
Output Characteristics Current Sourcing



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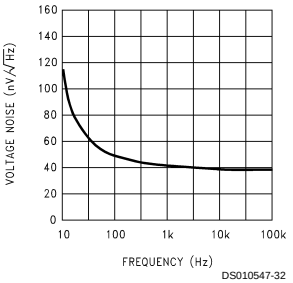
Input Voltage Noise vs Frequency



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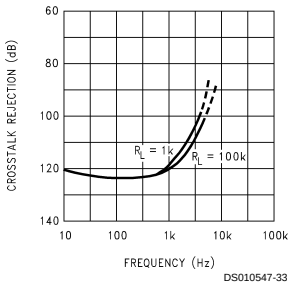
Crosstalk Rejection vs Frequency



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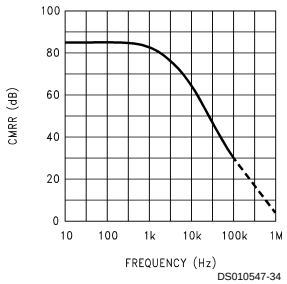
CMRR vs Frequency



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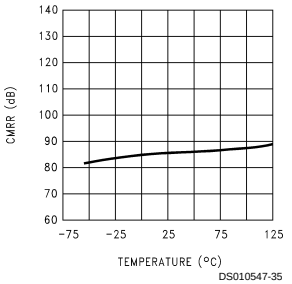
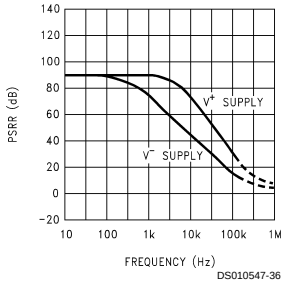
CMRR vs Temperature



DS010547-35

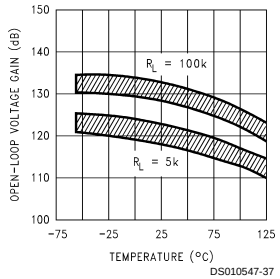
Power Supply Rejection Ratio vs Frequency



DS010547-36

Typical Performance Characteristics V_S = ± 7.5V, T_A = 25˚C unless otherwise specified (Continued)

Open-Loop Voltage Gain vs Temperature



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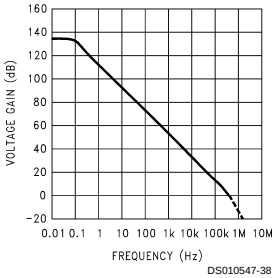
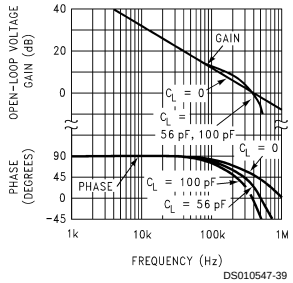
Open-Loop Frequency Response



DS010547-38

Gain and Phase Responses vs Load Capacitance



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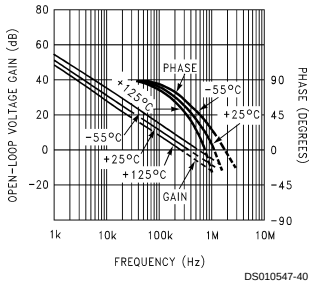
Gain and Phase Responses vs Temperature



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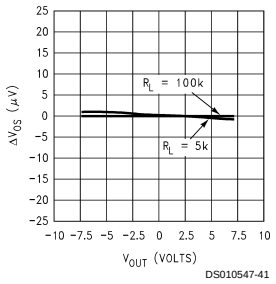
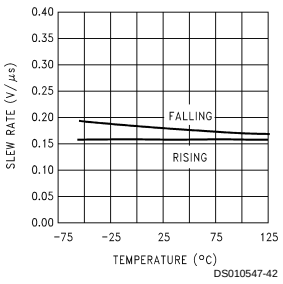
Gain Error (V_{OS} vs V_{OUT})



DS010547-41

Non-Inverting Slew Rate vs Temperature



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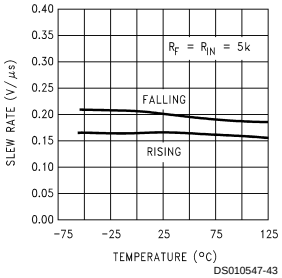
Inverting Slew Rate vs Temperature



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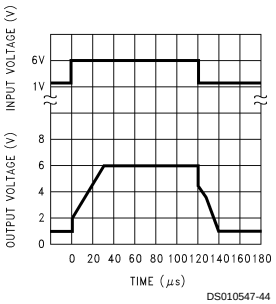
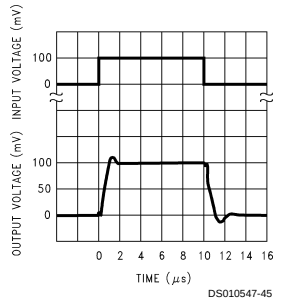
Large-Signal Pulse Non-Inverting Response (A_V = +1)



DS010547-44

Non-Inverting Small Signal Pulse Response (A_V = +1)

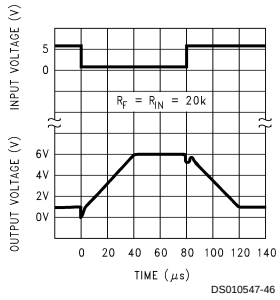


DS010547-45

Typical Performance Characteristics

V_S = ± 7.5V, T_A = 25˚C unless otherwise specified (Continued)

Inverting Large-Signal Pulse Response



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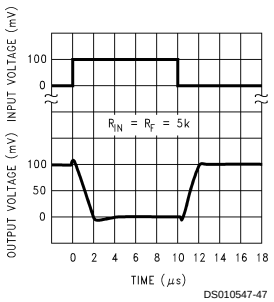
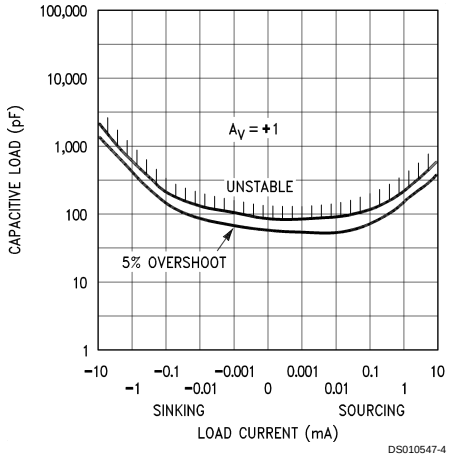
Inverting Small-Signal Pulse Response



DS010547-47

Stability vs Capacitive Load



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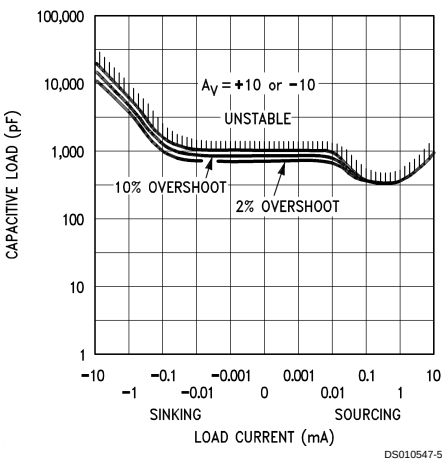
Note: Avoid resistive loads of less than 500Ω, as they may cause instability.

Stability vs Capacitive Load



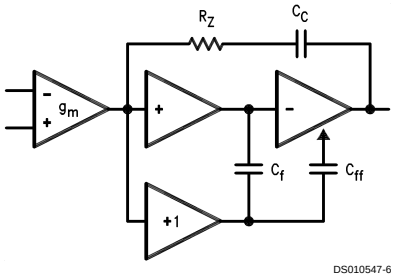
DS010547-5

Application Hints

AMPLIFIER TOPOLOGY

The topology chosen for the LPC660 is unconventional (compared to general-purpose op amps) in that the traditional unity-gain buffer output stage is not used; instead, the output is taken directly from the output of the integrator, to allow rail-to-rail output swing. Since the buffer traditionally delivers the power to the load, while maintaining high op amp gain and stability, and must withstand shorts to either rail, these tasks now fall to the integrator.

As a result of these demands, the integrator is a compound affair with an embedded gain stage that is doubly fed forward (via C_f and C_{ff}) by a dedicated unity-gain compensation driver. In addition, the output portion of the integrator is a push-pull configuration for delivering heavy loads. While sinking current the whole amplifier path consists of three gain stages with one stage fed forward, whereas while sourcing the path contains four gain stages with two fed forward.



DS010547-6

FIGURE 1. LPC660 Circuit Topology (Each Amplifier)

The large signal voltage gain while sourcing is comparable to traditional bipolar op amps, for load resistance of at least 5 kΩ. The gain while sinking is higher than most CMOS op

Application Hints (Continued)

amps, due to the additional gain stage; however, when driving load resistance of 5 kΩ or less, the gain will be reduced as indicated in the Electrical Characteristics. The op amp can drive load resistance as low as 500Ω without instability.

COMPENSATING INPUT CAPACITANCE

Refer to the LMC660 or LMC662 datasheets to determine whether or not a feedback capacitor will be necessary for compensation and what the value of that capacitor would be.

CAPACITIVE LOAD TOLERANCE

Like many other op amps, the LPC660 may oscillate when its applied load appears capacitive. The threshold of oscillation varies both with load and circuit gain. The configuration most sensitive to oscillation is a unity-gain follower. See the Typical Performance Characteristics.

The load capacitance interacts with the op amp's output resistance to create an additional pole. If this pole frequency is sufficiently low, it will degrade the op amp's phase margin so that the amplifier is no longer stable at low gains. The addition of a small resistor (50Ω to 100Ω) in series with the op amp's output, and a capacitor (5 pF to 10 pF) from inverting input to output pins, returns the phase margin to a safe value without interfering with lower-frequency circuit operation. Thus, larger values of capacitance can be tolerated without oscillation. Note that in all cases, the output will ring heavily when the load capacitance is near the threshold for oscillation.

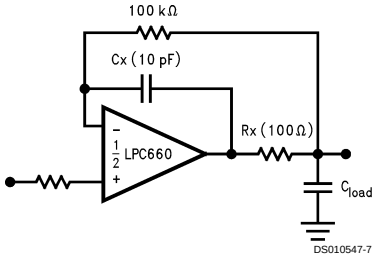


FIGURE 2. Rx, Cx Improve Capacitive Load Tolerance

Capacitive load driving capability is enhanced by using a pull up resistor to V^+ (*Figure 3*). Typically a pull up resistor conducting 50 μA or more will significantly improve capacitive load responses. The value of the pull up resistor must be determined based on the current sinking capability of the amplifier with respect to the desired output swing. Open loop gain of the amplifier can also be affected by the pull up resistor (see Electrical Characteristics).

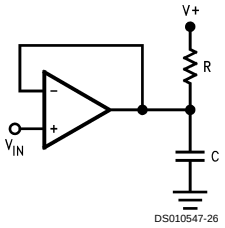


FIGURE 3. Compensating for Large Capacitive Loads with A Pull Up Resistor

PRINTED-CIRCUIT-BOARD LAYOUT FOR HIGH-IMPEDANCE WORK

It is generally recognized that any circuit which must operate with less than 1000 pA of leakage current requires special layout of the PC board. When one wishes to take advantage of the ultra-low bias current of the LPC660, typically less than 0.04 pA, it is essential to have an excellent layout. Fortunately, the techniques for obtaining low leakages are quite simple. First, the user must not ignore the surface leakage of the PC board, even though it may sometimes appear acceptably low, because under conditions of high humidity or dust or contamination, the surface leakage will be appreciable.

To minimize the effect of any surface leakage, lay out a ring of foil completely surrounding the LPC660's inputs and the terminals of capacitors, diodes, conductors, resistors, relay terminals, etc. connected to the op-amp's inputs. See *Figure 4*. To have a significant effect, guard rings should be placed on both the top and bottom of the PC board. This PC foil must then be connected to a voltage which is at the same voltage as the amplifier inputs, since no leakage current can flow between two points at the same potential. For example, a PC board trace-to-pad resistance of 10^{12} ohms, which is normally considered a very large resistance, could leak 5 pA if the trace were a 5V bus adjacent to the pad of an input. This would cause a 100 times degradation from the LPC660's actual performance. However, if a guard ring is held within 5 mV of the inputs, then even a resistance of 10^{11} ohms would cause only 0.05 pA of leakage current, or perhaps a minor (2:1) degradation of the amplifier's performance. See *Figure 5a*, *Figure 5b*, *Figure 5c*for typical connections of guard rings for standard op-amp configurations. If both inputs are active and at high impedance, the guard can be tied to ground and still provide some protection; see *Figure 5d*.

Application Hints (Continued)

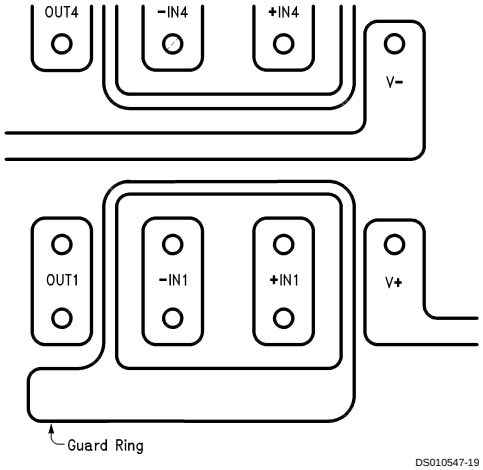
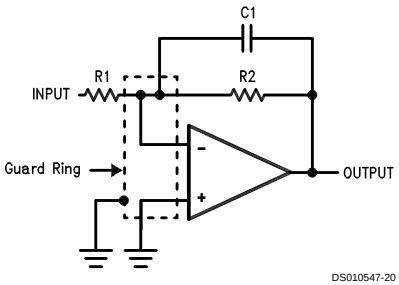
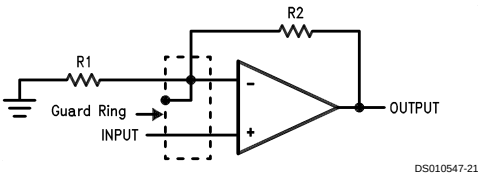


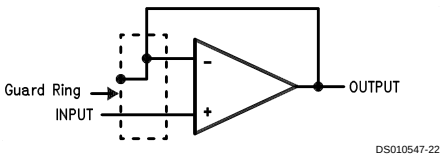
FIGURE 4. Example of Guard Ring in P.C. Board Layout using the LPC660



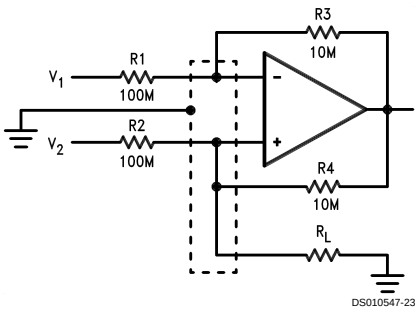
(a) Inverting Amplifier



(b) Non-Inverting Amplifier



(c) Follower

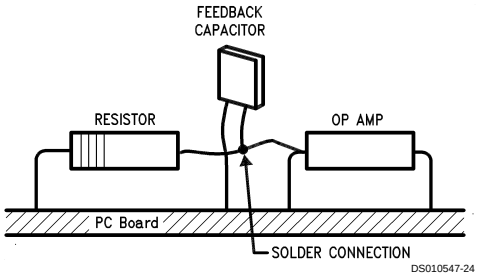


(d) Howland Current Pump

FIGURE 5. Guard Ring Connections

The designer should be aware that when it is inappropriate to lay out a PC board for the sake of just a few circuits, there is another technique which is even better than a guard ring on a PC board: Don't insert the amplifier's input pin into the board at all, but bend it up in the air and use only air as an insulator. Air is an excellent insulator. In this case you may have to forego some of the advantages of PC board construction, but the advantages are sometimes well worth the effort of using point-to-point up-in-the-air wiring. See *Figure 6*.

Application Hints (Continued)



(Input pins are lifted out of PC board and soldered directly to components. All other pins connected to PC board.)

FIGURE 6. Air Wiring

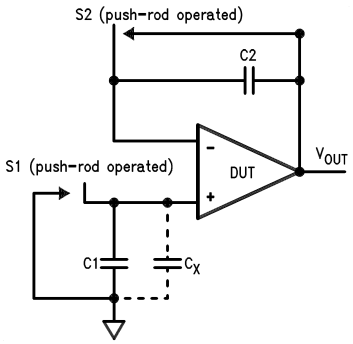


FIGURE 7. Simple Input Bias Current Test Circuit

BIAS CURRENT TESTING

The test method of *Figure 7* is appropriate for bench-testing bias current with reasonable accuracy. To understand its operation, first close switch S2 momentarily. When S2 is opened, then

$$I^- = \frac{dV_{OUT}}{dt} \times C2.$$

A suitable capacitor for C2 would be a 5 pF or 10 pF silver mica, NPO ceramic, or air-dielectric. When determining the magnitude of I^-, the leakage of the capacitor and socket must be taken into account. Switch S2 should be left shorted most of the time, or else the dielectric absorption of the capacitor C2 could cause errors.

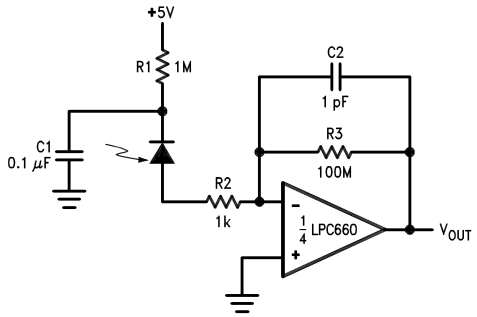
Similarly, if S1 is shorted momentarily (while leaving S2 shorted)

$$I^+ = \frac{dV_{OUT}}{dt} \times (C1 + C_x)$$

where C_x is the stray capacitance at the + input.

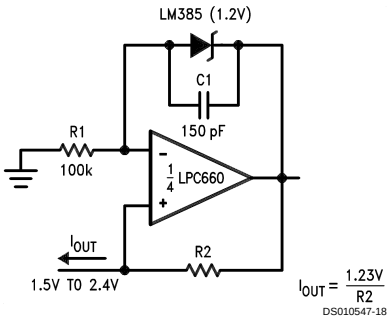
Typical Single-Supply Applications ($V^+ = 5.0\ V_{DC}$)

Photodiode Current-to-Voltage Converter



Note: A 5V bias on the photodiode can cut its capacitance by a factor of 2 or 3, leading to improved response and lower noise. However, this bias on the photodiode will cause photodiode leakage (also known as its dark current).

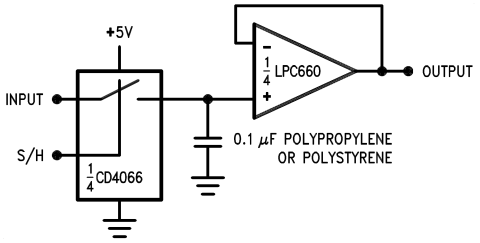
Micropower Current Source



Note: (Upper limit of output range dictated by input common-mode range; lower limit dictated by minimum current requirement of LM385.)

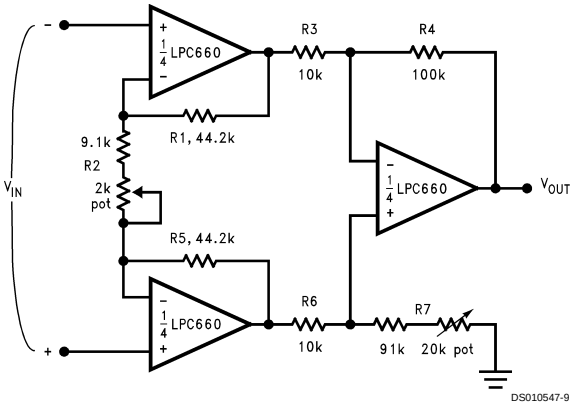
Typical Single-Supply Applications (V^+ = 5.0 V_{DC}) (Continued)

Low-Leakage Sample-and-Hold



DS010547-8

Instrumentation Amplifier



DS010547-9

If R1 = R5, R3 = R6, and R4 = R7;

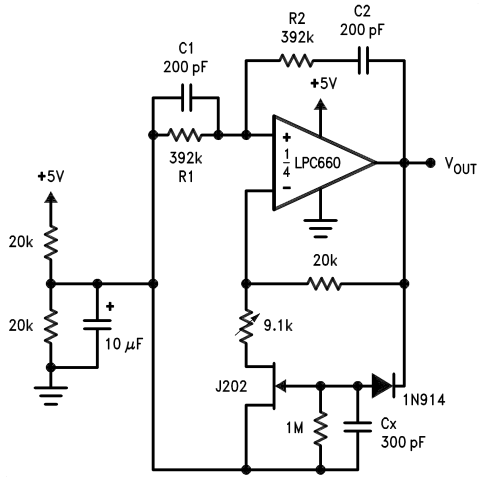
then $\frac{V_{OUT}}{V_{IN}} = \frac{R2 + 2R1}{R1} \times \frac{R4}{R3}$

$\therefore A_V \approx 100$ for circuits shown.

For good CMRR over temperature, low drift resistors should be used. Matching of R3 to R6 and R4 to R7 affects CMRR. Gain may be adjusted through R2. CMRR may be adjusted through R7.

Typical Single-Supply Applications (V^+ = 5.0 V_{DC}) (Continued)

Sine-Wave Oscillator



DS010547-10

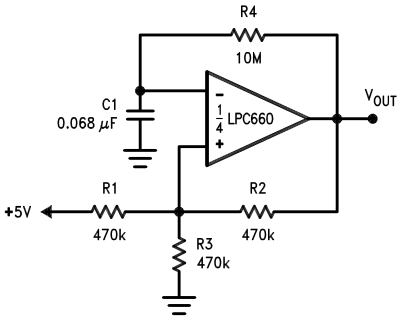
Oscillator frequency is determined by R1, R2, C1, and C2:

f_{OSC} = 1/2πRC

where R = R1 = R2 and C = C1 = C2.

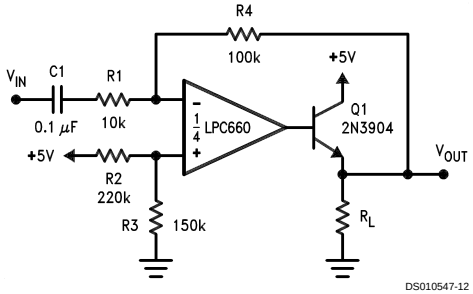
This circuit, as shown, oscillates at 2.0 kHz with a peak-to-peak output swing of 4.5V

1 Hz Square-Wave Oscillator



DS010547-11

Power Amplifier



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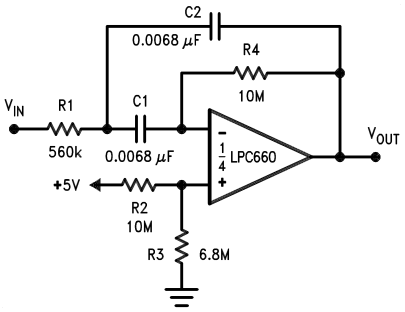
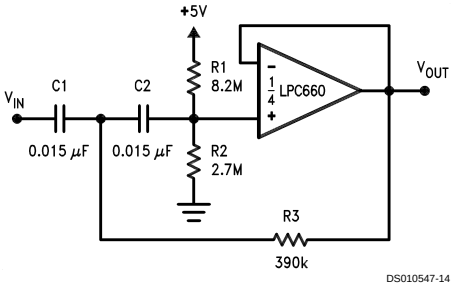
Typical Single-Supply Applications (V^+ = 5.0 V_{DC}) (Continued)

10 Hz Bandpass Filter



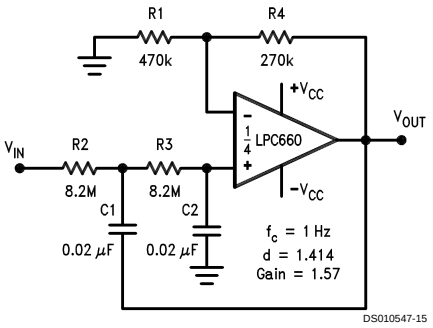
f_O = 10 Hz
Q = 2.1
Gain = −8.8

10 Hz High-Pass Filter (2 dB Dip)

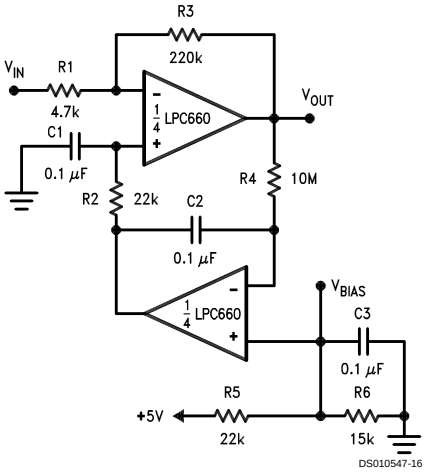


f_c = 10 Hz
d = 0.895
Gain = 1

1 Hz Low-Pass Filter
(Maximally Flat, Dual Supply Only)

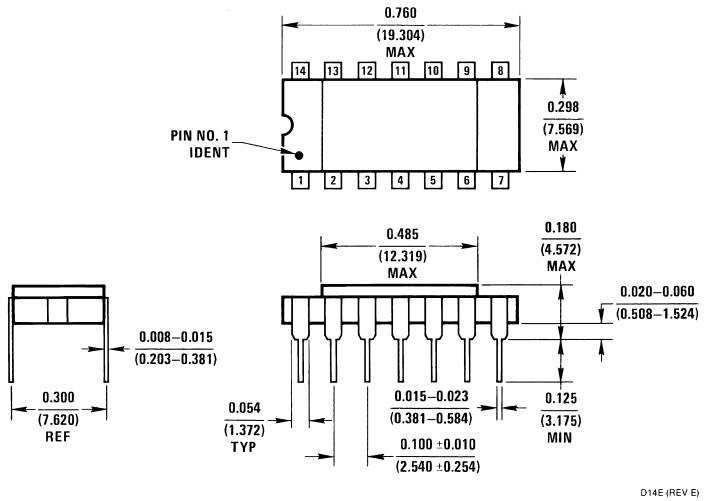


High Gain Amplifier with Offset Voltage Reduction

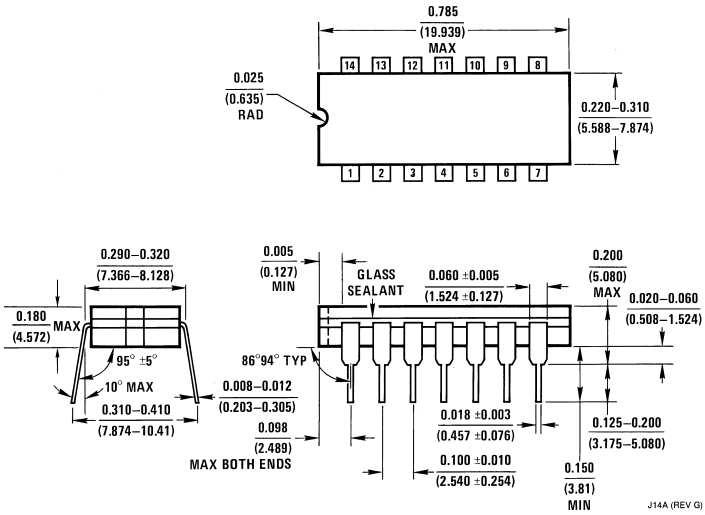


Gain = −46.8
Output offset voltage reduced to the level of the input offset voltage of the bottom amplifier (typically 1 mV), referred to V_{BIAS}.

Physical Dimensions inches (millimeters) unless otherwise noted

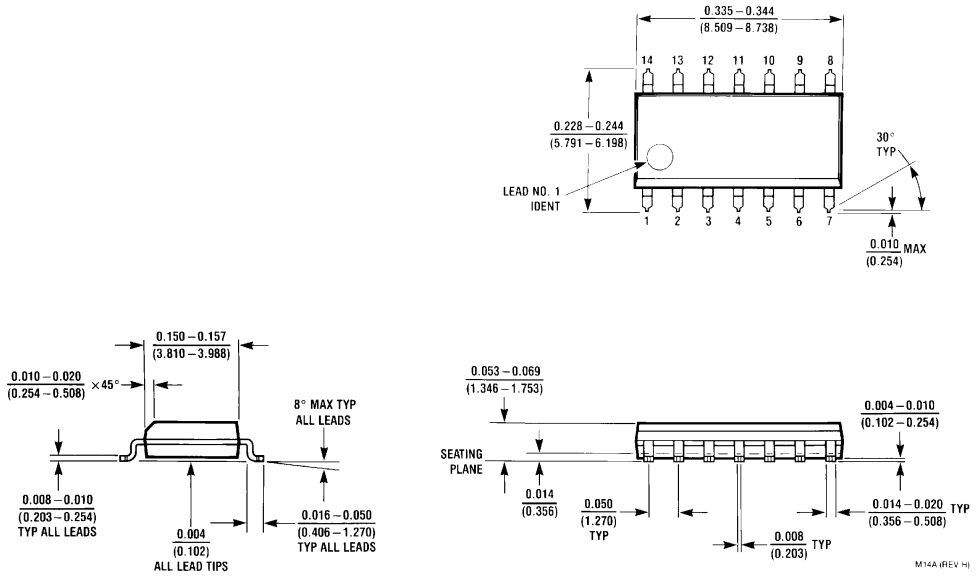


14-Pin Cavity Dual-In-Line Package (D)
Order Number LPC660AMD
NS Package Number D14E

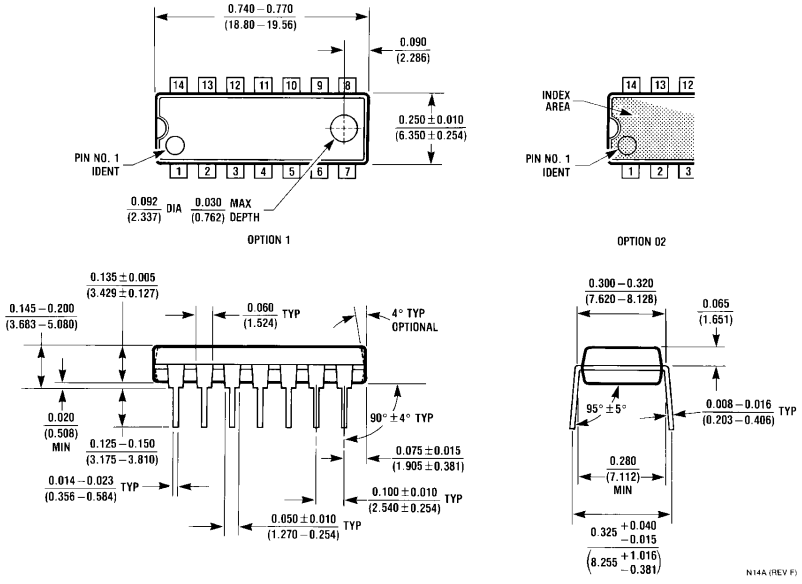


14-Lead Ceramic Dual-In-Line Package (J)
Order Number LPC660AMJ/883
NS Package Number J14A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



14-Pin Small Outline Molded Package (M)
Order Number LPC660AIM or LPC660IM
NS Package Number M14A



14-Pin Molded Dual-In-Line Package (N)
Order Number LPC660AIN or LPC660IN
NS Package Number N14A

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